

HEAT-SENSITIVE PRESSURE-SENSITIVE ADHESIVE COMPOSITION AND HEAT-SENSITIVE PRESSURE-SENSITIVE ADHESIVE SHEET

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Abstract of JP1085269

PURPOSE: To obtain the title composition which undergoes no blocking even just after application, by mixing an aqueous dispersion of a polymeric resin with a aqueous dispersion of a tackifier and an aqueous dispersion of a solid plasticizer.

CONSTITUTION: An aqueous dispersion (A) of 100pts.wt. polymer resin comprising at least 1pt.wt. ethylene/vinyl acetate copolymer (a) of a vinyl acetate content ≤ 20 wt.% and, optionally, other resins (b) is mixed with an aqueous dispersion of 10-200pts.wt. tackifier (B) (e.g., rosin ester), preferably, of a softening point (JIS K 5903) of 70-145 deg.C and an aqueous dispersion of 50-300pts.wt. solid plasticizer (C) (e.g., dicyclohexyl phthalate), and the resulting mixture is optionally diluted with water to obtain the title composition which is an aqueous resin dispersion of a solid matter content of 25-60wt.% and a solid particle diameter of 0.05-5 μ m. This composition is applied to a base sheet in the form of a water-based paint and dried to obtain a heat-sensitive pressure-sensitive adhesive sheet.

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